

Title (en)

A METHOD AND APPARATUS FOR MANUFACTURING MULTI-LAYER CIRCUIT BOARDS.

Title (de)

VERFAHREN UND VORRICHTUNG ZUR HERSTELLUNG MEHRSCICHTIGER SCHALTUNGSBRETTER.

Title (fr)

PROCEDE ET APPAREIL DE FABRICATION DE PLAQUES MULTI-COUCHES DE CIRCUITS.

Publication

**EP 0103627 A4 19850918 (EN)**

Application

**EP 83901286 A 19830304**

Priority

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Abstract (en)

[origin: WO8303065A1] Methods and apparatus (48) for providing fine line, high density multiple layer printed circuit board packages (44). In the method for fabricating multiple layer printed circuit board package (44), a printed circuit board (42) is formed having a conductive circuit pattern (18) embedded in and integral with an insulator material substrate (32), such that the surface of the conductive circuit pattern is exposed along one surface (34) of the substrate, and lays flush and coplanar therewith. At least two of said boards (42) are stacked with a layer of insulator material (44) interposed between each pair of adjacent boards (42). The entire assembly is heat-pressed together to form a homogeneous block of insulator material having conductive circuit patterns embedded and integrally molded therein.

IPC 1-7

**B05D 5/12**; **B32B 31/00**; **B44C 1/22**; **C03C 15/00**; **C23F 1/00**; **C25D 5/02**; **H05K 1/00**

IPC 8 full level

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CPC (source: EP)

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Citation (search report)

- [X] GB 1259837 A 19720112 - BOEING CO [US]
- [X] GB 964349 A 19640722 - ROGERS CORP
- [E] EP 0080689 A2 19830608 - IBM [US]
- [A] IBM TECHNICAL DISCLOSURE BULLETIN, vol. 24, no. 6, November 1981, page 2796, New York, US; S.W. COBURN: "Use of SF6-O2 discharges for plasma-desmearing drilled holes in printed circuit boards"

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AT BE CH DE FR GB LI LU NL SE

DOCDB simple family (publication)

**WO 8303065 A1 19830915**; CA 1222574 A 19870602; DK 502783 A 19831103; DK 502783 D0 19831103; EP 0103627 A1 19840328; EP 0103627 A4 19850918; IN 158376 B 19861101; IT 1163136 B 19870408; IT 8319877 A0 19830303; IT 8319877 A1 19840903; JP S59500341 A 19840301; NO 834009 L 19831103

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**US 8300292 W 19830304**; CA 422703 A 19830302; DK 502783 A 19831103; EP 83901286 A 19830304; IN 272CA1983 A 19830304; IT 1987783 A 19830303; JP 50124183 A 19830304; NO 834009 A 19831103